Chips and Change

How Crisis Reshapes the Semiconductor Industry

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The MIT Press Cambridge, Massachusetts London, England

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This book was set in Sabon on 3B2 by Asco Typesetters, Hong Kong and was printed and bound in the United States of America.

Library of Congress Cataloging-in-Publication Data

Brown, Clair, 1946-

Chips and change: how crisis reshapes the semiconductor industry / Clair Brown and Greg Linden.

p. cm

Includes bibliographical references and index.

ISBN 978-0-262-01346-8 (hbk. : alk. paper) 1. Semiconductor industry—

Management. 2. Business cycles. I. Linden, Greg, 1959 II. Title.

HD9696.S42B76 2009

338.4′762138152dc22 2009007072

10 9 8 7 6 5 4 3 2 1

Acknowledgments

The authors thank the Alfred P. Sloan Foundation, the Institute for Research on Labor and Employment at UC Berkeley, and the Institute for Technology, Enterprise and Competitiveness (ITEC/COE) at Doshisha University, Japan, for their support during the many years of the research for this book.

This book represents the knowledge gained through the Sloan Competitive Semiconductor Manufacturing Program at UC Berkeley, directed by David Hodges, then Dean of Engineering, and Robert Leachman. Clair Brown joined the project as head of the human resources group in 1991. Along with an extraordinary group of faculty and graduate students, they spent six years together in the field benchmarking and analyzing semiconductor fabrication. The insights and knowledge gained from working with Hodges and Leachman are to be found throughout the book, along with the invaluable contributions from CSM team members over the years, especially Melissa Appleyard, Diane Bailey, Neil Berglund, Michael Borrus, Benjamin Campbell, Robert Cole, Henry Chesbrough, Jumbi Edulbehram, Rosemarie Ham Ziedonis, Nile Hatch, Jeffrey Macher, David Mowery, Yongwook Paik, Yooki Park, Greg Pinsonnault, Daniel Rascher, Michael Reich, David Teece, Jihong Sanderson, Linda Sattler, Amy Shuen, Vince Valvano, and Katalin Voros. We have also benefited enormously over the years from discussions with and feedback from Gail Pesyna, Frank Mayadas, and Ralph Gomory from the Sloan Foundation.

We are also deeply indebted to many engineers and semiconductor experts outside UCB who have shared their time and expertise with us, especially Hisao Baba, Hiroyuki Chuma, Robert Doering, Jean-Philippe x

Dauvin, David Ferrell, Michael Flynn, Venugopal Gopinathan, Norikazu Hashimoto, Paul Horn, Toshiaki Masuhara, Elena Obukhova, Makoto Onodera, Toshihiko Osada, William Spencer, Makoto Sumita, Yasuhiro Takada, Andrew Viterbi, and C.-K. Wang.

Our research in other countries could not have been accomplished without the expertise, help, and guidance provided by our colleagues Yoshifumi Nakata, Hugh Whittaker, and Eiichi Yamaguchi, along with Philippe Byosiere, Toshiro Kita, James Lincoln, Mon-Han Tsai, Tsuyoshi Tsuru in Japan; Sandra del Boca in Italy; Yea-Huey Su in Taiwan; Ling Huang and Josh Chen in China; and Poornima Shenoy and the India Semiconductor Association in India.

We are also grateful to Gartner, Global Semiconductor Alliance, Ron Hira, G.Dan Hutcheson, iSuppli, Daya Nadamuni, Ed Pausa, Devadas Pillai, SEMI, the Semiconductor Industry Association, Chintay Shih, Gary Smith, Tim Tredwell and anonymous reviewers for their valuable contributions.

Jason Dedrick, Rafiq Dossani, Richard Freeman, Deepak Gupta, Bradford Jensen, Ken Kraemer, Frank Levy, B. Lindsay Lowell, Tom Murtha, Deepak Somaya, Tim Sturgeon, and Michael Teitelbaum, along with participants at the NAE Workshop on the Offshoring of Engineering and the 2005 Brookings Trade Forum on Offshoring of White-Collar Work and participants at seminar presentations at the Berkeley Innovation Seminar, Doshisha ITEC, Japan Electronics and Information Technologies Industry Association (JEITA), Institute for Innovation Research at Hitotsubashi University, and Association of Super-Advanced Electronics Technologies (ASET) provided thoughtful discussions that improved various chapters.

Dozens of industry participants, interviewed under a confidentiality agreement, have patiently provided us with hours of education and insights, without which this book would not be possible, and unfortunately we cannot thank them by name. Special thanks go to the excellent staff of the electronics trade press, whose work is noted throughout the book. Their efforts helped us understand technologies and keep abreast of business developments.

We have been drawn to the study of the semiconductor industry for many years because it is an exciting industry in constant change. Perhaps even more important for engaging us intellectually has been the amazing engineers we met along the way. These engineers are tireless in their dedication to pushing chip technology and applications forward, and their talents, energy, and knowledge have made being out in the field an intellectual and personal treat. We are especially grateful to them, both as researchers and as users of chips.

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